L Number	Hits	Search Text	DB	Time stamp
1	172	73/856.ccls.	USPAT	2002/01/25 16:32
2	615	425/144.ccls.	USPAT;	2002/01/25 16:33
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
8	699	318/560.ccls.	USPAT;	2002/01/25 16:33
١	099	310/300.ccis.		2002/01/25 10.55
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
14	2	318/560.ccls. and (mold near clamp\$5)	USPAT;	2002/01/25 16:34
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	164	73/856.ccls.	USPAT	2002/01/25 16:32
_	10	73/856.ccls. and mold	USPAT	2001/02/26 09:38
-				1
-	5	73/856.ccls. and (mold molding) and (injection inject pressure)	USPAT	2001/02/26 09:36
-	40553	(injection pressure) and (molding mold ) and (device	USPAT;	2001/02/26 09:42
		apparatus machine).clm.	EPO; JPO;	
			DERWENT;	
		•	IBM_TDB	
_	9162	(injection pressure) and (molding mold ) and (device	USPAT;	2001/02/26 15:12
	0102	apparatus machine) and (control controls).clm.	EPO; JPO;	2001/02/20 10.12
		apparatus macrine) and (control controls).cim.		
			DERWENT;	
			IBM_TDB	
-	21	((injection pressure) and (molding mold ) and (device	USPAT;	2001/07/24 13:34
		apparatus machine) and (control controls) and sensor and	EPO; JPO;	
		switch ).clm.	DERWENT,	
			IBM_TDB	:
_	4	((injection pressure) and (molding mold ) and (device	USPAT:	2001/02/26 10:00
-	~			2001/02/20 10.00
		apparatus machine) and (control controls) and (force pressure	EPO; JPO;	:
		strain) near4 sensor and switch ).clm.	DERWENT;	
			IBM_TDB	
-	10	(injection pressure) and (molding mold) and (device	USPAT;	2001/02/27 13:41
		apparatus machine) and (control controls) and (subtractor	EPO; JPO;	
		substractor).clm.	DERWENT;	
			IBM_TDB	
_	2	((injection pressure) and (molding mold ) and (device	USPAT;	2001/02/27 13:45
	_			2001/02/21 10.40
		apparatus machine) and (control controls)and (subtractor	EPO; JPO;	
		substractor)and (clamp clamping)).clm.	DERWENT;	
			IBM_TDB	
-	1	((injection pressure) and (molding mold) and (device	USPAT;	2001/02/27 13:45
		apparatus machine) and (control controls)and (subtractor	EPO; JPO;	
		substractor)and (clamp clamping)and sensor).clm.	DERWENT:	•
			IBM_TDB	
_	26	("4131596" "4506321" "4714867" "5274316" "5313151"	USPAT;	2001/07/23 17:05
1	20			200 1101120 11.00
1		"5341452" "5362222" "5444341" "5583411").pn.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	27	("3864557" "3870445" "3878372" "3937776" "4094940"	USPAT;	2001/07/23 17:06
		"4311446" "5232714" "5237509").pn.	EPO; JPO;	
		· ·	DERWENT;	
			IBM_TDB	
_	1	((injection pressure) and (molding mold ) and (device	USPAT;	2001/07/24 14:01
-	•			2001/01/24 14.01
		apparatus machine) and (control controls) and force near2	EPO; JPO;	
		sensor and switch ).clm.	DERWENT;	
			IBM_TDB	
-	1	((injection pressure) near2 (molding mold ) near2 (device	USPAT;	2001/07/24 14:41
		apparatus machine) and (control controls) and force near2	EPO; JPO;	
Θ		sensor).clm.	DERWENT;	
		oundry.out.		
	4	(/inication accesses) and (maldisc access) access (day) -	IBM_TDB	2004/07/04 44 00
-	1	((injection pressure) near2 (molding mold ) near2 (device	USPAT;	2001/07/24 14:06
		apparatus machine) and (control controls controller) and force	EPO; JPO;	
		near2 sensor).clm.	DERWENT;	
			IBM TDB	İ

		1.05/00		
-	17	425/\$6.ccls. and ((injection pressure) near2 (molding mold) near2 (device apparatus machine) and (control controls) and force near2 sensor)	USPAT; EPO; JPO;	2002/01/25 16:32
		loice flear Serisory	DERWENT;	
-	10	425/\$6.ccls. and ((injection pressure) near2 (molding mold)	USPAT;	2001/07/24 14:49
		near2 (device apparatus machine) and (control controls) and	EPO; JPO;	2001/01/24 14.49
		force near sensor)	DERWENT;	
			IBM_TDB	
-	1	425/\$6.ccls. and ((injection pressure) near2 (molding mold)	USPAT;	2001/07/24 14:53
		near2 (device apparatus machine) and (control controls) and	EPO; JPO;	
		force near sensor) and platen	DERWENT;	
_	0	425/\$6 cols, and ((injection procesure) peer? (molding mold.)	IBM_TDB	0004/07/04 44-50
_		425/\$6.ccls. and ((injection pressure) near2 (molding mold) and (control controls) and ((force near sensor) near4 platen))	USPAT;	2001/07/24 14:56
		did (control controls) and (horce flear sensor) flear4 plateir))	EPO; JPO; DERWENT;	
			IBM_TDB	
-	0	425/\$6.ccls. and ((injection pressure) near2 (molding mold)	USPAT;	2001/07/24 14:56
ī		and (control controls) and ((force near sensor) near6 platen))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1	425/\$6.ccls. and ((injection pressure) near2 (molding mold)	USPAT;	2001/07/24 14:57
		and (control controls) and ((force near sensor) and platen))	EPO; JPO;	
			DERWENT;	
-	0	425/\$6.ccls. and ((injection pressure) near2 (molding mold)	IBM_TDB USPAT;	2001/07/24 14:58
		and (clamp\$4) near2 ((force near sensor) and platen))	EPO; JPO;	2001/01/24 14.56
		(in the country is the control of the place in the country)	DERWENT;	
			IBM_TDB	r
-	1	425/\$6.ccls. and ((injection pressure) near2 (molding mold)	USPAT;	2001/07/24 14:58
		and (clamp\$4) and ((force near sensor) and platen))	EPO; JPO;	
			DERWENT;	
	_	425/\$6 colo and ((injection processes) many (soulding processes)	IBM_TDB	0004/07/04/4 #0
-	0	425/\$6.ccls. and ((injection pressure) near2 (molding mold) and (clamp\$4) near6 ((force near sensor) and platen))	USPAT;	2001/07/24 14:59
		and (clamp\$4) heard ((lorce hear sensor) and platen))	EPO; JPO; DERWENT;	
			IBM_TDB	
-	88	425/\$6.ccls. and ((injection pressure) near2 (molding mold)	USPAT;	2001/07/24 14:59
		and (clamp\$4) near6 force and sensor and platen)	EPO; JPO;	
			DERWENT;	
		405/001	IBM_TDB	
•	4	425/\$6.ccls. and ((injection pressure) near2 (molding mold )	USPAT;	2001/07/24 15:06
		and (clamp\$4) near6 force near4 sensor and platen)	EPO; JPO;	
			DERWENT;	
-	4	425/\$6.ccls. and ((injection pressure) near2 (molding mold)	USPAT;	2001/07/25 13:17
		and (clamp\$4 near6 force) and (force near4 sensor) and	EPO; JPO;	2001/01/20 10:17
		platen)	DERWENT;	
			IBM_TDB	
-	19	("3870445" "5371450" "5912025" "5632222" "4131596") .pn.	USPAT;	2001/07/25 13:27
			EPO; JPO;	
			DERWENT;	
_	19	/"3870AA5" "5371A50" "5042025" "5262222" "4424506"\	IBM_TDB	2004/07/05 40:00
-	ושו	("3870445" "5371450" "5912025" "5362222" "4131596") .pn.	USPAT;	2001/07/25 13:28
			EPO; JPO;   DERWENT;	
			IBM_TDB	
	L		1 .5	